

Preliminary Datasheet

N+P-Channel 30-V (D-S) MOSFET

FEATURES

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

Application

- Portable Devices
- Consumer Electronics

Mechanical

●Case: SOP-8-Dual Package

Packing Information

| Package | Packing |
|------------|-------------|
| SOP-8-Dual | 3K/13" Reel |

| Maximum Ratings (T _A =25°C unless otherwise specified) | | | | | | |
|---|-----------------------------------|------------|------------|----|--|--|
| Parameter | Symbol | Lir | Limit | | | |
| | | N-Channel | P-Channel | | | |
| Drain-Source Voltage | V _{DS} | 30 | -30 | V | | |
| Gate-Source Voltage | V _{GS} | ±20 | ±20 | V | | |
| Continuous Drain Current ¹⁾ | Ι _D | 6 | -5 | А | | |
| Maximum Power Dissipation | P _D | 1.2 | 1.1 | W | | |
| Pulsed Drain Current ²⁾ | I _{DM} | 24 | -20 | А | | |
| ng Junction and Storage Temperature | T _J , T _{STG} | -55 to 150 | -55 to 150 | °C | | |

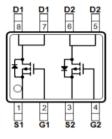
| Typical Thermal Resistance | | | | | | | |
|--|-----------------------|-----|------|--|--|--|--|
| Parameter Symbol Limit Unit | | | | | | | |
| Junction-to-Ambient Thermal Resistance | $R_{	extsf{	heta}JA}$ | 110 | °C/W | | | | |

Note:

R0JA is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper

| PRODUCTY SUMMARY | | | | | |
|------------------|----|------------------------|--------------------|--|--|
| V _{DS} | R | _{DS(on)} m(Ω) | I _D (A) | | |
| 30 | 30 | Rdson @10V | 6.0 | | |
| 30 | 50 | Rdson @4.5V | 5.0 | | |
| -30 | 50 | Rdson @-10V | -5.0 | | |
| | 70 | Rdson @-4.5V | -4.1 | | |







| Electrical Characteristics ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED) | | | | | | |
|---|---------------------|--|--------|-----|------|--------|
| Characteristics | Symbol | Test Condition | Limits | | | l In:t |
| Characteristics | | | Min | Тур | Max | Unit |
| N-Channel Static | | | | | | |
| Drain-Source Breakdown Voltage | B _{VDSS} | $V_{GS} = 0V, I_D = -250uA$ | 30 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS}=V_{GS}$, $I_{D}=-250uA$ | 1 | - | 2.5 | V |
| | R _{DS(on)} | V _{GS} =10.0V, I _D =6.0A | - | 21 | 30 | mΩ |
| Drain-Source On-State Resistance | | V _{GS} =4.5V, ID=5.0A | - | 35 | 50 | mΩ |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =30V, V _{GS} =0V | - | - | 1.0 | uA |
| Gate-Source Leakage Current | I _{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ±100 | nA |
| Drain-Source Diode | | | | | | |
| Diode Forward Voltage | V_{SD} | I _S =0.8A, V _{GS} =0V | - | - | 1.2 | V |

| Electrical Characteristics ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED) | | | | | | |
|---|---------------------|--|--------|-----|-------|------|
| Characteristics | Symbol | Test Condition | Limits | | | Unit |
| Characteristics | | | Min | Тур | Max | Onit |
| P-Channel Static | | | | | | |
| Drain-Source Breakdown Voltage | B _{VDSS} | $V_{GS} = 0V, I_D = -250uA$ | -30 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | V_{DS} =VGS, I_{D} =-250uA | -1.00 | - | -2.50 | V |
| | R _{DS(on)} | V _{GS} =-10.0V, I _D =-5.0A | - | 38 | 50 | mΩ |
| Drain-Source On-State Resistance | | V _{GS} =-4.5V, ID=-4.1A | - | 54 | 70 | mΩ |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-30V, V _{GS} =0V | - | - | -1.0 | uA |
| Gate-Source Leakage Current | I _{GSS} | V_{GS} =±20V, V_{DS} =0V | - | - | ±100 | nA |
| Drain-Source Diode | | | | | | |
| Diode Forward Voltage | V_{SD} | I _S =-0.8A, V _{GS} =0V | - | - | -1.2 | V |

NOTES :

1. Pulse width<300us, Duty cycle<2%

2. Essentially independent of operating temperature typical characteristics.

3. R_{QJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper

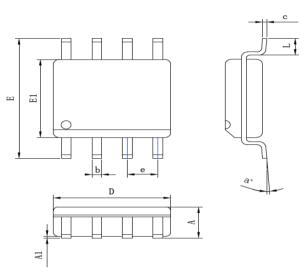
4. The maximum current rating is package limited

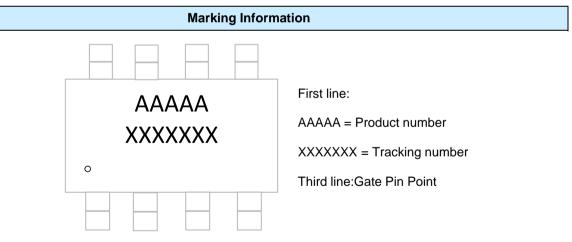
5. Guaranteed by design, not subject to production testing



Package Outline Dimensions (inches and millimeters)

| SOP-8 | | | | | | |
|--------|---------|--------|--------|-------|--|--|
| | | Dime | nsions | | | |
| SYMBOL | Millir | neters | Inches | | | |
| | Min | Max | Min | Max | | |
| А | - | 1.75 | | 0.069 | | |
| A1 | 0.10 | 0.23 | 0.004 | 0.009 | | |
| b | 0.35 | 0.48 | 0.014 | 0.019 | | |
| с | 0.19 | 0.25 | 0.007 | 0.010 | | |
| D | 4.70 | 5.10 | 0.185 | 0.201 | | |
| E | 5.80 | 6.20 | 0.228 | 0.244 | | |
| E1 | 3.70 | 4.10 | 0.146 | 0.161 | | |
| е | 1.27bsc | | | | | |
| L | 0.50 | 0.80 | 0.020 | 0.031 | | |
| a° | 0 ° | 8 ° | 0 ° | 8 ° | | |





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